

Title (en)

Method for making a planar multi-layer metal bonding pad.

Title (de)

Verfahren zur Herstellung einer metallischen Planar-Bondfläche mit mehreren Schichten.

Title (fr)

Procédé pour la fabrication d'un plat de contact planaire métallique à multicouche.

Publication

EP 0519665 A1 19921223 (EN)

Application

EP 92305470 A 19920615

Priority

US 71645491 A 19910617

Abstract (en)

A method is provided for planarizing a multi-layer metal bonding pad. A first metal layer (13) is provided. A first dielectric layer (14) is provided with a multitude of vias (17) covering the first metal layer (13), thereby exposing portions of the first metal layer (13) through the multitude of vias (17) in the first dielectric (14). A second metal layer (18) is deposited on the first dielectric layer (14) making electrical contact to the first metal layer through the multitude of vias (17). Planarization of the second metal layer (18) is achieved by having the second metal layer (18) cover the first dielectric layer (14) and making contact through the vias (17). <IMAGE>

IPC 1-7

H01L 23/485

IPC 8 full level

H01L 21/60 (2006.01); **H01L 23/485** (2006.01)

CPC (source: EP US)

H01L 23/485 (2013.01 - EP US); **H01L 24/03** (2013.01 - EP US); **H01L 24/05** (2013.01 - EP US); **H01L 2224/02166** (2013.01 - EP US); **H01L 2224/05556** (2013.01 - EP US); **H01L 2924/00014** (2013.01 - EP US); **H01L 2924/01004** (2013.01 - EP US); **H01L 2924/01013** (2013.01 - EP US); **H01L 2924/01014** (2013.01 - EP US); **H01L 2924/01022** (2013.01 - EP US); **H01L 2924/01029** (2013.01 - EP US); **H01L 2924/01033** (2013.01 - EP US); **H01L 2924/01074** (2013.01 - EP US); **H01L 2924/14** (2013.01 - EP US)

C-Set (source: EP US)

H01L 2924/00014 + **H01L 2224/05556**

Citation (search report)

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- [A] EP 0291014 A2 19881117 - TOSHIBA KK [JP]
- [A] EP 0431490 A1 19910612 - TOSHIBA KK [JP], et al

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DE FR GB

DOCDB simple family (publication)

US 5149674 A 19920922; DE 69226819 D1 19981008; DE 69226819 T2 19990422; EP 0519665 A1 19921223; EP 0519665 B1 19980902; JP 2970232 B2 19991102; JP H05243321 A 19930921; US 5287002 A 19940215

DOCDB simple family (application)

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